

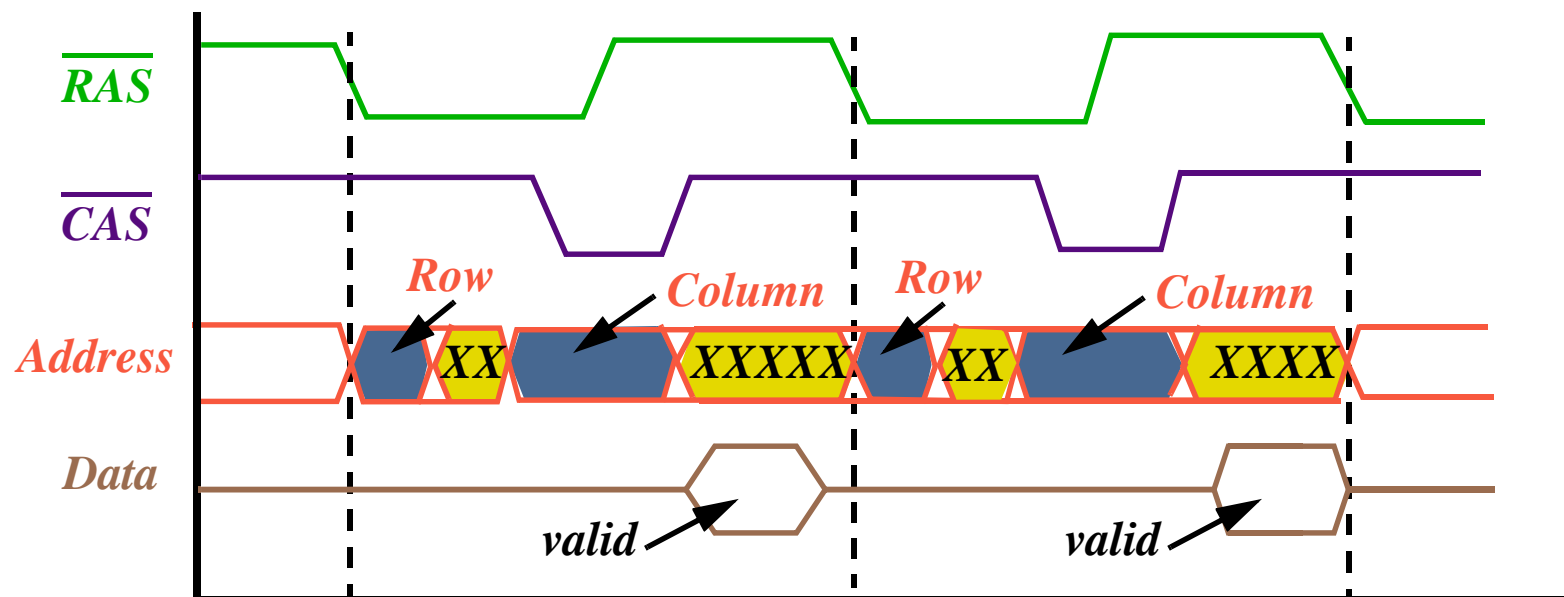
## More on DRAM

### DRAM Chip Operating Modes

Memory chips can execute one or more column modes to reduce access time

### Normal Mode

The timing diagram recaps what we have seen before about normal access to the DRAM chips



## *DRAM Operating Modes*

### *Page Mode*

The page mode is a high-speed memory access mode

One the RAS signal is provided to the memory, the whole memory row is read on to the internal data wires

If the next memory access refers to a memory location in the same row but another column, it is not necessary to input and decode the row address again

Thus in page mode, the column address is changed but the row address remains the same

To start read the memory controller activates the RAS signal and transfers the row address

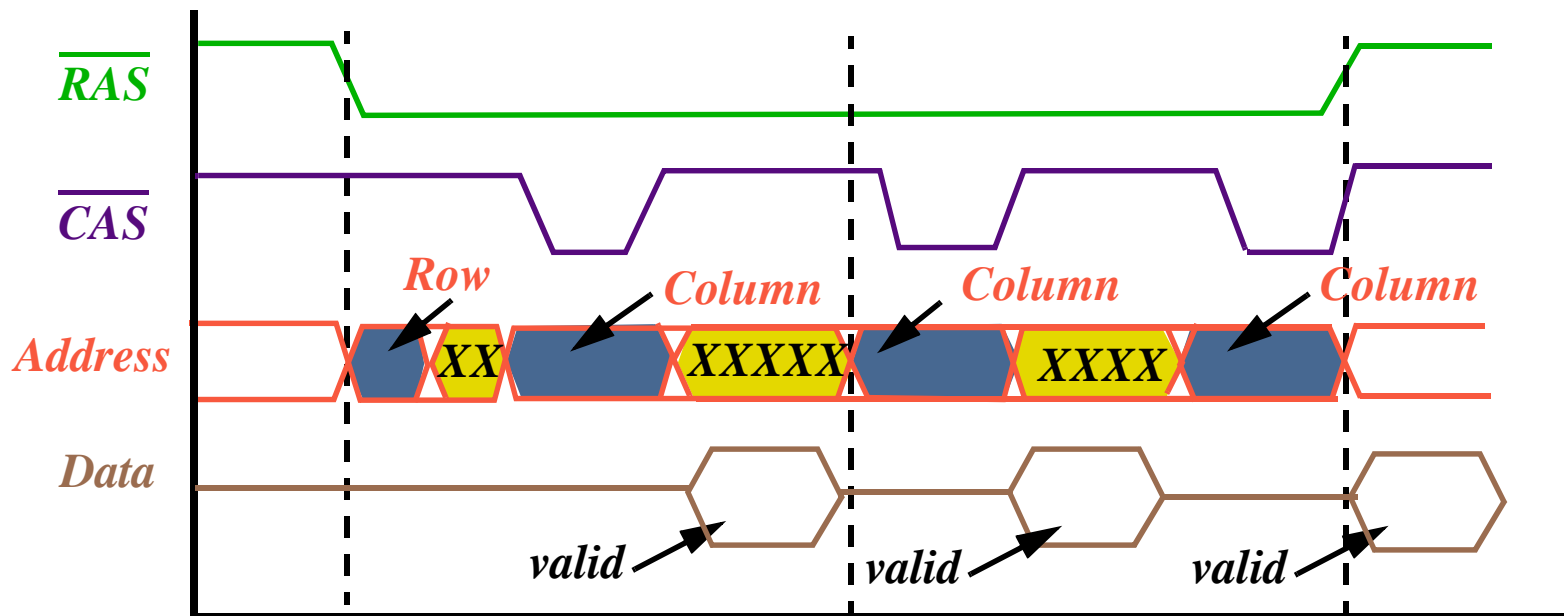
Next the CAS signal is activated and the column address is provided

The RAS signal is not deactivated once the data is read, as in normal mode

## DRAM Operating Modes

### Page Mode

Rather the CAS is deactivated for a short time and a new column address is provided and the next CAS strobe



This makes memory accesses faster, the access times is about 50% and the cycle time is about 70% shorter than normal mode

## *DRAM Operating Modes*

### *Page Mode*

However, this performance increase is only for the second and all subsequent accesses

For stability purpose, the RAS signal cannot remain active for a indefinite period of time

Typically, 200 accesses within the same page can be carried out before the memory controller has to deactivate the RAS signal for one cycle

Page mode accesses are not limited to read only as shown on the previous slide

Data may be written in page mode

Read and write operations within the same page can be mixed

Usually RAM is implemented such that a 1MB chip usually has about 1024 locations per page

If memory system is implemented as 32 bits (32 1MB chips) the page is 4Kb

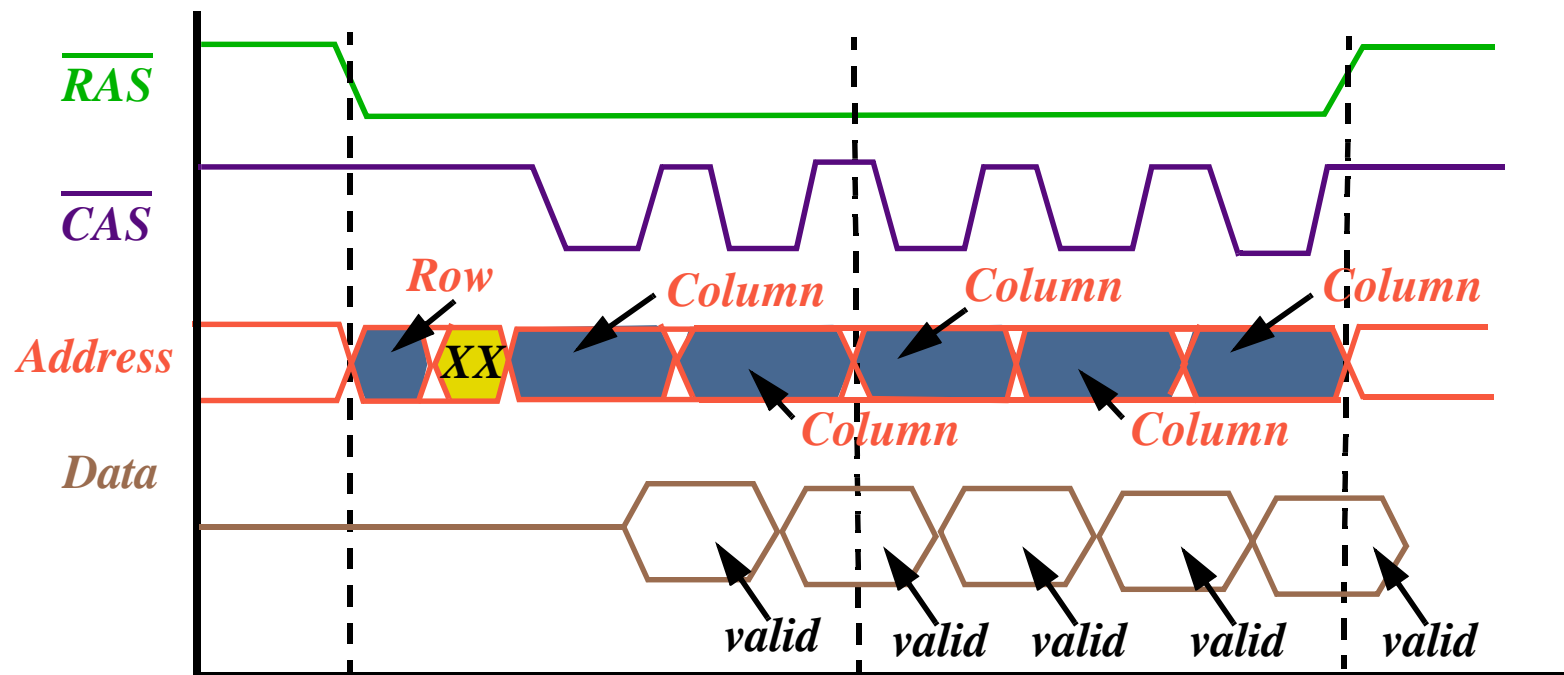
The page size is significant and memory accesses are usually done in blocks close to each other, so page mode is very useful

## DRAM Operating Modes

### Hyper Page Mode (EDO Mode)

In hyper page mode, also known as EDO mode, the time between two consecutive CAS activations is shorter than in normal page mode.

Column addresses are transferred more quickly, access time is shortened significantly (about 30%) providing higher transfer rates.



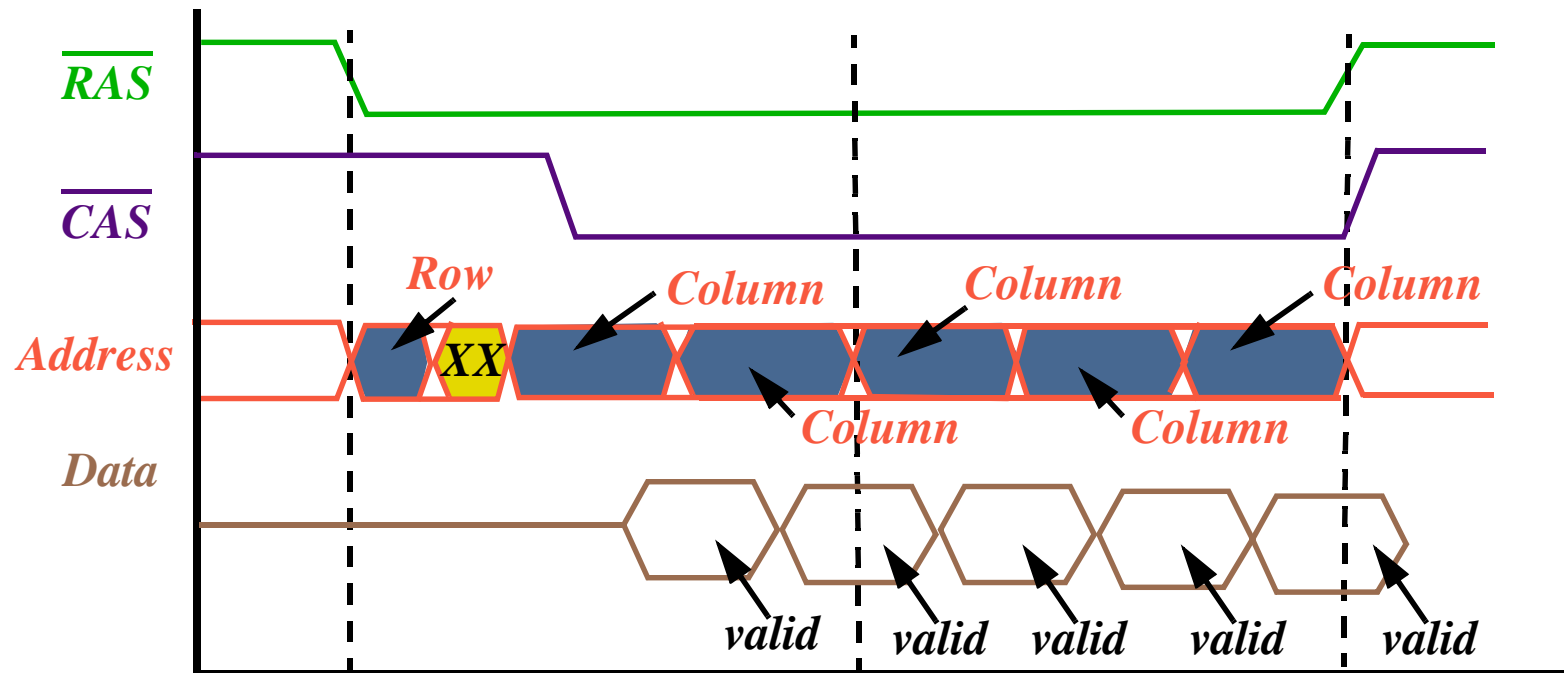
## DRAM Operating Modes

### Static Column Mode

Very similar to page mode, however CAS is no longer switched.

Only the column address is changed by the DRAM controller and the DRAM logic is intelligent enough to detect the change and provide new data providing more savings

Both CAS and RAS have to be deactivated after a finite period of time



## *DRAM Operating Modes*

### *Interleaving*

Another way to avoid delays because of the RAS precharge time is memory interleaving

The memory is divided into several banks interleaved at a particular ratio

For e.g., for i386 the memory is 2 way-interleaved

With 2-ways interleaving memory is divided into two banks that are each 32-bit wide (size of the data bus)

All data with even double-word addresses is located in bank 0 and all data with odd double-word addresses in bank 1.

We can still access any byte out of the double-word that we want

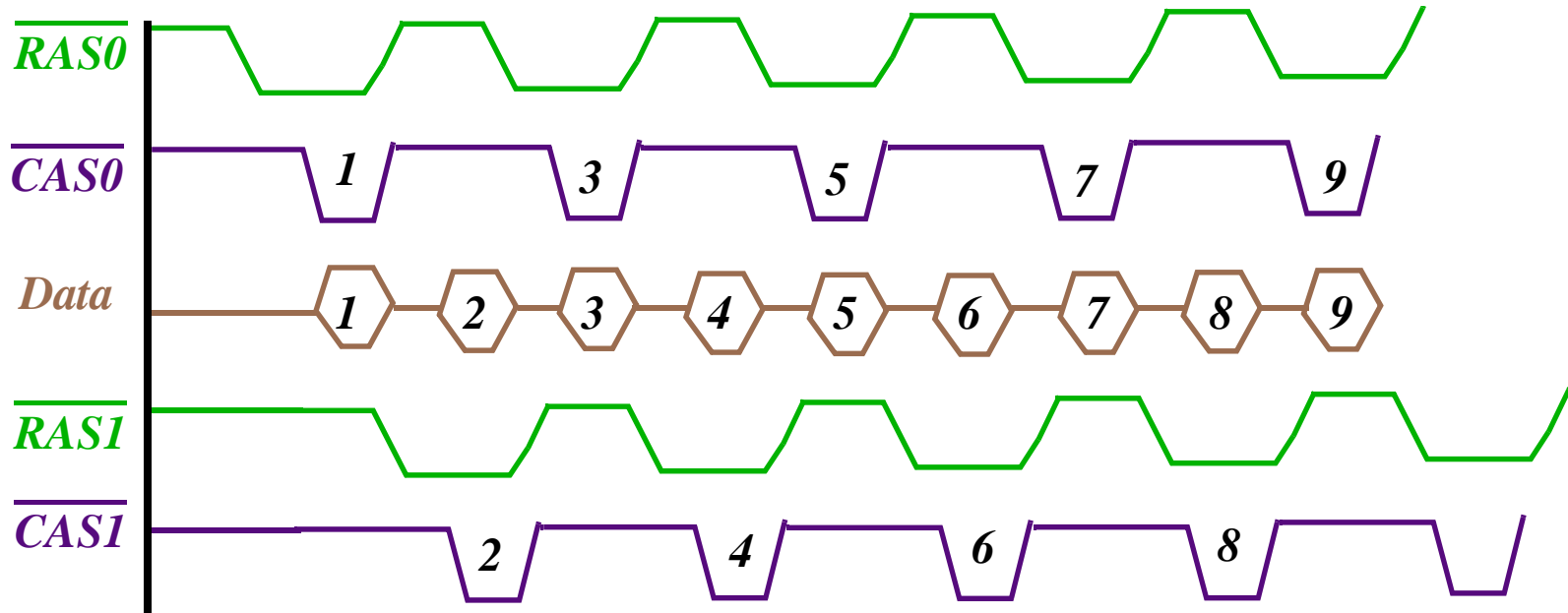
However, interleaving is less effective if the program works with byte-sized data

With interleaving, the i386 prefetcher, accesses the two banks alternately

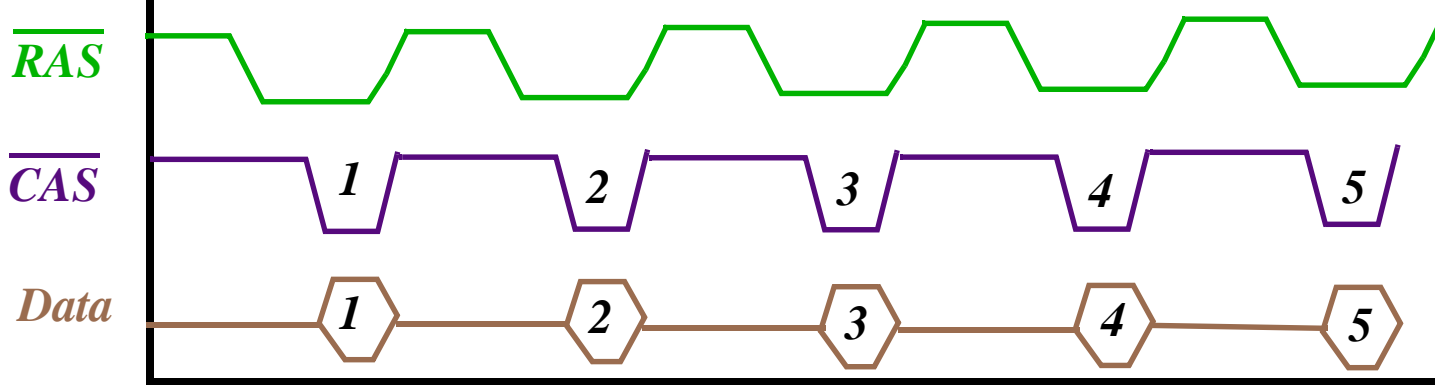
RAS precharge time of one bank overlaps with the access time of the other bank

*DRAM Operating Modes*

*Interleaving*



*Without Interleaving*

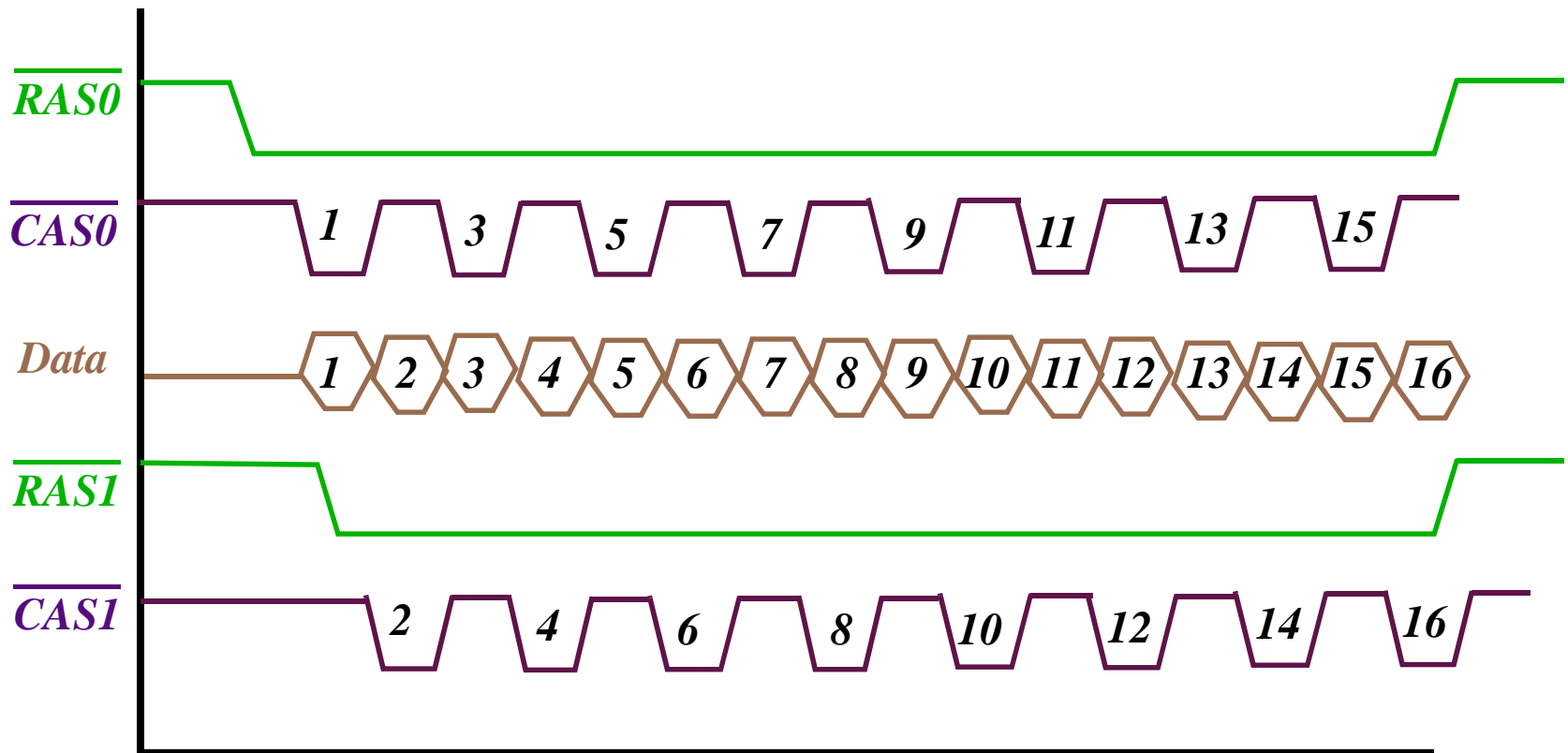




## DRAM Operating Modes

### Interleaving and Page Mode

Page mode can be used in conjunction to interleaving, thus providing even better performance than either stand-alone



## *SDRAM and DDR SDRAM*

### *SDRAM: Synchronous DRAM, DDR SDRAM: Double Data Rate SDRAM*

(Don't confuse this with SRAM. This is still a dynamic RAM)

SDRAM have typical access time of 8 to 15 ns (even lower now) as compared to the previously discussed EDO RAM which has access time of 50 to 60ns

The difference is noticeable with higher front side bus speeds found in today's boards

For SDRAMs, 168-pin DIMM sockets are used as memory modules with 64 bit data

SDRAMs work in burst mode and with a synchronous clock rate

They do not use the corresponding RAS, CAS, WE and CE signals

Rather commands such as write, read or burst stop are transferred

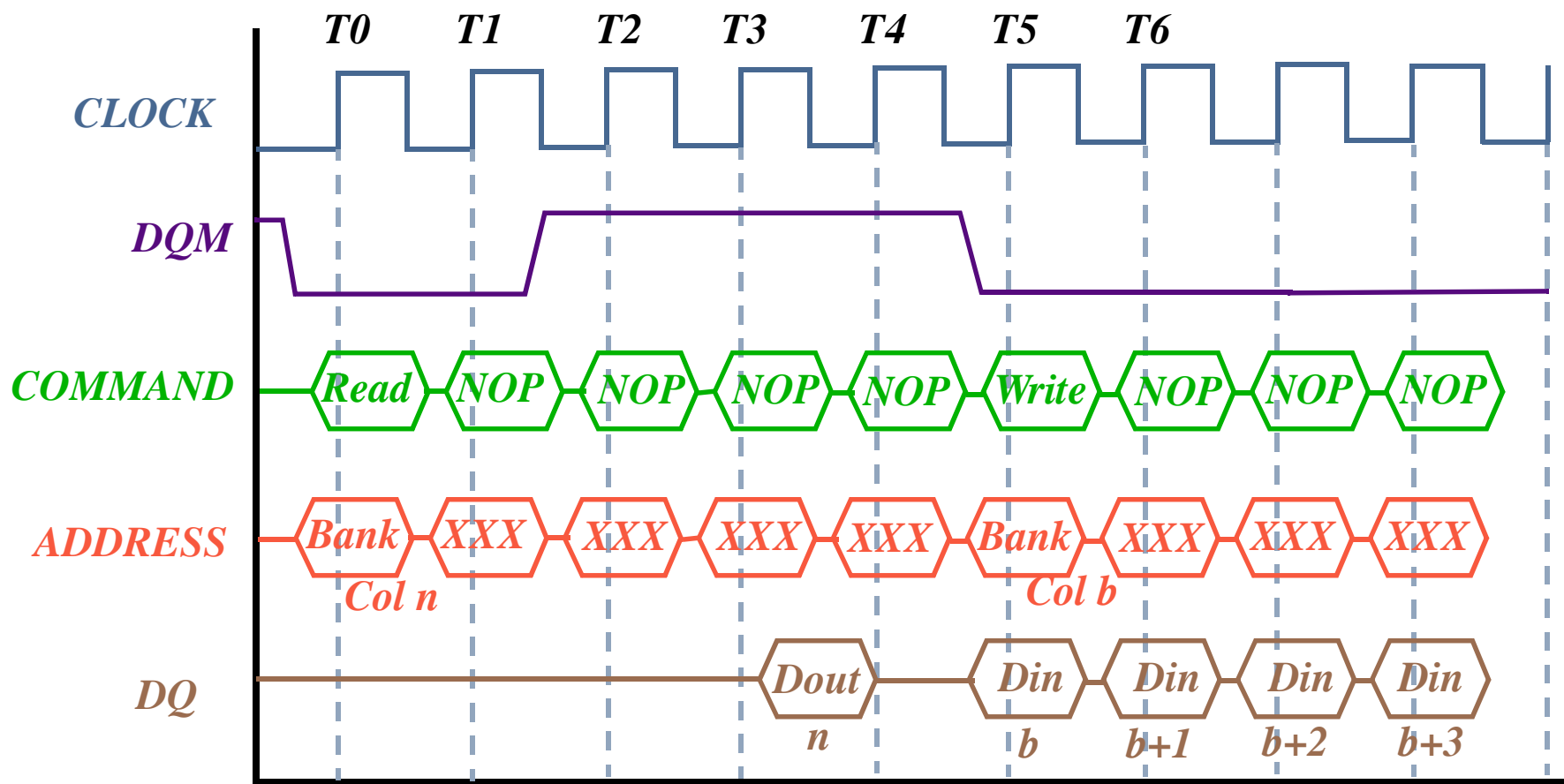
Some have a EEPROM, which contain data about the module type, organization of the DRAMs used and timing behavior.

Chipset's system management can read this info and configure the best settings

**SDRAM and DDR SDRAM**

The data transfer rate can be doubled if data is transferred on both the rising and falling edge of the clock signal

This is the principal used for **DDR SDRAMs**.



## *RAMBus*

RAMBus modules are known as RIMMs (rambus inline memory modules)

184 contacts, available capacities 64, 128, 256 MB (even bigger available)

The clock speeds are higher, but they use the same concept as DDR SDRAM, transfer data on both the clock edges

As the name, *Bus* implies, the entire memory architecture is a bus system.

Consists of the controller on one side, the memory chips (RDRAM) in the middle and a terminator at the other end

Maximum of 32 RDRAM chips can be present per module

No RIMM socket can be left empty, otherwise the bus would be incomplete and nothing would work

Historically RAMBus has been more expensive than DDR SDRAMs, and is used mainly in high end workstations and servers (running with XEON processors)

## *FLASH Memory*

FLASH memory is very important for today's computer systems

Used as the boot ROM, firmware storage for cards and also as removable storage

Several types of FLASH memories are available, mainly classified by the erasure and storage procedures

### *Bulk Erase FLASH*

The complete storage array is arranged as a single block

Whenever an erase is performed, the contents of all storage locations is cleared

### *Boot Block FLASH*

Most modern computers do not use the bulk erase flash devices

Instead a Boot Block FLASH device is used, that provides capabilities to erase individual blocks of storage locations

However, blocks on a boot device are not similar in size

## *FLASH Memory*

### *Boot Block FLASH (contd.)*

There is a small block called the *boot block*

Used mainly to store the boot code for the system

Following this are two small blocks called *parameter blocks*

Intended use is to store system parameters, e.g. system configuration table or lookup table

Finally, there are a number of much larger blocks or memory called *main blocks*, where the firmware code is stored

Boot block devices are used for a variety of applications that require smaller memory capacity and benefit from the asymmetrical blocking e.g. *in-system programming*

### *FlashFile FLASH*

This differ from boot block flash in that the memory array is organized into equal sized blocks, with control to erase each block individually

They are referred to as symmetrically blocked and used in design of high-density devices, for large storage of code or data e.g. *FLASH memory drive*